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Semtech's Backward Compatibility Statement

September 15, 2009

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- Semtech Corporation is aware of the increasing environmental concerns being raised with electronic products containing lead-based interconnections. Semtech supports the voluntary reduction and subsequent elimination of lead in electronic products, including component lead plating finishes. There are often questions relating to the use of lead-free products. This note covers the use of lead-free products being mixed with lead based parts during board reflow.
- **What reflow temperature would be used in this scenario?**
- Semtech lead-free parts can be mixed with leaded parts and reflowed at a lower temperature (less than or equal to 240 °C) with proper reflow conditions and compatible solder paste. Reflow temperature of greater than 240 °C can negatively affect the reliability of leaded parts so is not recommended.
- **What is the solder paste currently used by most SMT (Surface Mount Technology) Manufacturers for leaded PC board reflow?**
- Current PC board reflow uses eutectic solder Sn63/Pb37. This solder is also compatible with Matte Tin and Ni/Pd/Au plated parts.
- **What about Flip Chip and BGA products?**
- Lead-free Flip Chip and BGA products cannot be mixed with leaded parts and reflowed at lower temperature.
- Semtech Corporation will work with customers where assistance is required with a lead-free component finish.
- If you would like additional information on our progress or would like to request a lead-free component finish on selected products, please contact your local sales office.

A handwritten signature in black ink, appearing to read 'Pat Sanchez'.

Pat Sanchez

Manager, Corporate Quality